

CURRENT 1.0 Ampere
 VOLTAGE RANG 50 to 1000 Volts

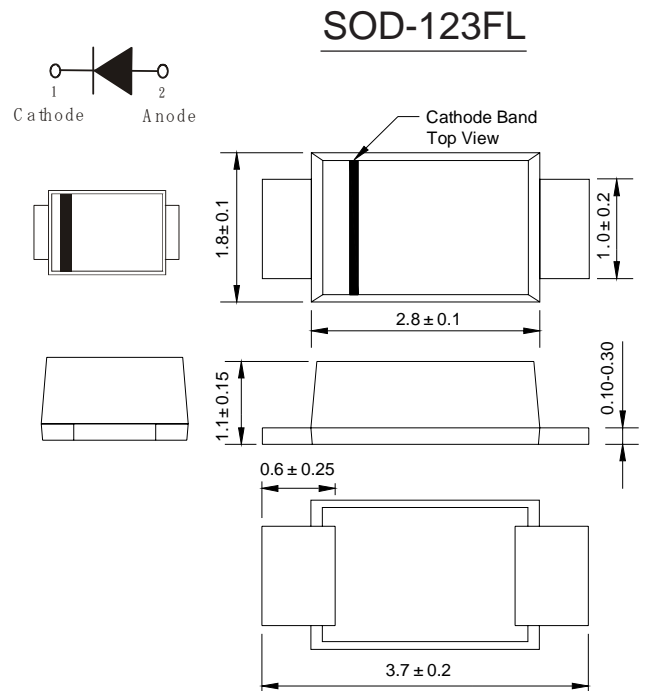
F1A THRU F1M

FEATURES

- Low profile space
- Ideal for automated placement
- Glass passivated chip junctions
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

MECHANICAL DATA

- Case:** JEDEC SOD-123FL molded plastic body over glass passivated chip
- Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- Polarity:** Laser band denotes cathode end



Dimensions in millimeters

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(TA = 25 °C unless otherwise noted)

	Symbol	F1A	F1B	F1D	F1G	F1J	F1K	F1M	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{F(AV)}$	1							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	25							A
Maximum instantaneous forward voltage at 1.0A	V_F	1.3							V
Maximum DC reverse current at Rated DC blocking voltage	I_R	5.0 50							μ A
Maximum reverse recovery time at $I_F = 0.5$ A , $I_R = 1.0$ A , $t_{rr} = 0.25$ A	t_{rr}	150				250	500		nS
Typical junction capacitance at 4.0 V ,1MHz	C_J	15							p F
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							°C

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RATING AND CHARACTERISTIC CURVES F1A Thru F1M

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

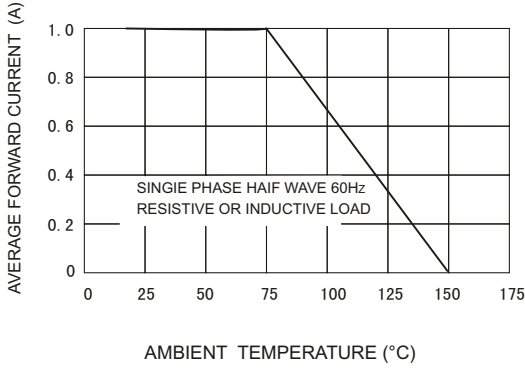


FIG.2-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

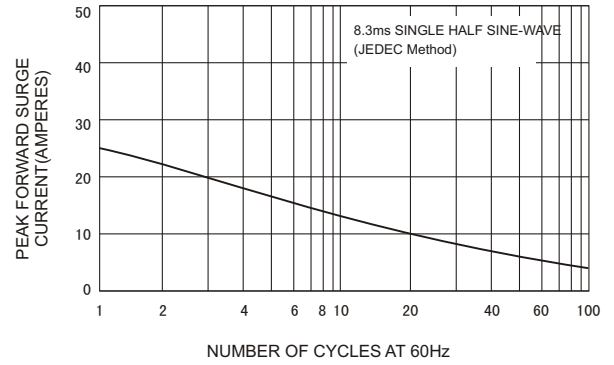


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

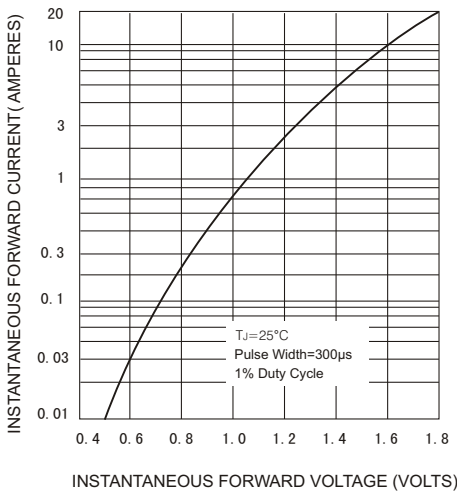


FIG.4-TYPICAL REVERSE CHARACTERISTICS

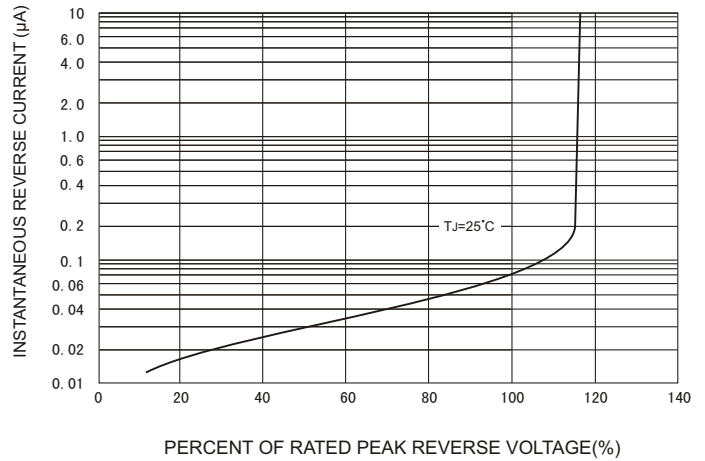


FIG.5-TYPICAL JUNCTION CAPACITANCE

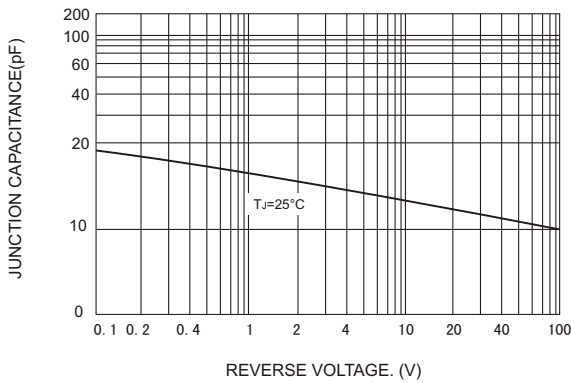


FIG.6-TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC

